

Rev. 1-10-03

Effective March 1998

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

() Original	() Supplemental	() Substitute	(X) PCT	() DESIGN
Congina	() Supplemental	() Jubstitute	(Λ) $\Gamma \cup \Gamma$	Opesion

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: NANOSIZE HEATER-MOUNTED NOZZLE AN	ID METHOD FOR MANUFACTURING S	AME AND METHOD FOR
FORMING MICRO THIN FILM		
of which is described and claimed in:	·	
() the attached specification, or		
() the specification in application Serial No.	. filed	, and with
amendments through, or		
(X) the specification in International Application No. PC (if applicable).	T/JP2004/015598, filed October 21, 2004,	and as amended on April 20, 2006
I hereby state that I have reviewed and understand the corany amendment(s) referred to above.	ntent of the above-identified specification, i	ncluding the claims, as amended by
I acknowledge my duty to disclose to the Patent and Traden in Title 37, Code of Federal Regulations, §1.56.	mark Office all information known to me to b	e material to patentability as defined
I hereby claim priority benefits under Title 35, United State for patent or inventor's certificate listed below and have all filing date before that of the application on which priority	lso identified below any application for pate	s for a Design) of any application(s) ent or inventor's certificate having a

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2003-362072	October 22, 2003	YES
Japan	2004-215944	July 23, 2004	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; Jeffrey R. Filipek, Reg. No. 41,471; and Douglas W. Hahm, Reg. No. 44,142, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S.

Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from <u>AOYAMA & PARTNERS</u> as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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Seiji AKITA 2nd Inventor Yoshikaru MARAYAMA	Date May 12, 2006 Date May 12, 2006
3rd Inventor	Date
4th Inventor	Date
5th Inventor	Date
6th Inventor	Date
The above application may be more particularly identified as follows:	
U.S. Application Serial No Filing	g Date April 20, 2006
Applicant Reference Number 546907 Atty Docket No. 2006 0598A	

Title of Invention NANOSIZE HEATER-MOUNTED NOZZLE AND METHOD FOR MANUFACTURING SAME AND METHOD FOR FORMING MICRO THIN FILM